Approved Minutes of the I.E.E.E. P1451.3 Working Group Teleconference

Date: Friday, August 14, 2002
Time: 10:00 AM PT (1:00 PM ET)

Acting Officers

Larry Malchodi, Chair
Lee Eccles, Editor

Agenda

Description

1 **Approve agenda & take attendance**
2 **Review and approve IEEE P1451.3/D1.17 for balloting.**
3 **Review and approve release of cover letter**.

Glossary

Chip	A spread spectrum term referring to a bit in the chipping code, which is a string of bits that evaluates to a single bit of the 'base band' or 'message' data.
DOCSIS	Data Over Cable Service Interface Specification
DotX	The IEEE 1451.X Standard
DTD	Document Type Definition (used with XML)
FDMA	Frequency Division Multiple Access
FPGA	Field Programmable Gate Array
HPNA	Home Phone Network Alliance (HomePNA)
HTML	Hyper Text Markup Language
ITU	International Telecommunications Union
NCAP	Network Capable Application Processor
NIST	National Institute of Standards & Technology
ORNL	Oak Ridge National Laboratory
QAM	Quadrature Amplitude Modulation
QPSK	Quadiphase-Shift Keying
Schema	A template structure similar to DTDs
SIG	Special Interest Group
TOD	Time Of Day
TBIM	Transducer Bus Interface Module
TBC	Transducer Bus Controller
UUID	Universal Unique Identifier
XML	Extensible Markup Language

1) Approve agenda & take attendance

Attendance was taken.

2) Review and approve IEEE P1451.3/D1.17 for balloting.

The draft version (D1.17) was discussed. None of the attendees indicated that they had any concerns with releasing the draft for balloting.

A motion was made to release the draft under D2.0 to the IEEE for balloting with the following changes:
- Fix reference to Annex F.3
- Fix column centering for some tables
- Fix some figures in clause 9 (lines & boxes)
- Syntax of XML schema will be corrected

This motion is a major technical issue and per the working group rules, a company vote was taken.

The motion was made by Charles Jones and seconded by Wayne Catlin.
There was no further discussion.
Motion approved: 8-Yes, 1-Not Present, 0 - No

Name	Company	Vote
Catlin, Wayne Eccles, Lee Malchodi, Larry Slack, Mark	Boeing	Yes
Licht, Torben	B & K	Yes
Owen, Allan	Eaton Corp.	Not present
GenKuong, Fernando	Endevco	Yes
Bække, Jørgen	Independent Consultant	Yes
Jones, Charles	Instrumentation Div. - Edwards AFB	Yes
Sinclair, Bob	NVE Corp.	Yes
Lenarduzzi, Roberto	ORNL	Yes
Maxwell, Daniel	Walden Technology Source, Inc.	Yes
	Motion Approved	Yes

3) **Review and approve release of cover letter**.

The ballot cover letter was discussed. None of the attendees indicated that they had any concerns with releasing the cover letter.

A motion was made to release it to the IEEE for balloting.

This motion is a major technical issue and per the working group rules, a company vote was taken.

The motion was made by Jørgen Bække and seconded by Torben Licht.
There was no further discussion.
Motion approved 8-Yes, 1-Not Present, 0 - No

Name	Company	Vote
Catlin, Wayne Eccles, Lee Malchodi, Larry Slack, Mark	Boeing	Yes
Licht, Torben	B & K	Yes
Owen, Allan	Eaton Corp.	Not present
GenKuong, Fernando	Endevco	Yes
Bække, Jørgen	Independent Consultant	Yes
Jones, Charles	Instrumentation Div. - Edwards AFB	Yes
Sinclair, Bob	NVE Corp.	Yes
Lenarduzzi, Roberto	ORNL	Yes
Maxwell, Daniel	Walden Technology Source, Inc.	Yes
	Motion Approved	Yes

4) Other

Patent Issues: The working group members were asked if anyone knew of anything in the proposed standard that might use patented technology. Torben mentioned B & K's patent concerning synchronization of a pair of wires. He agreed to send the working group a release letter per IEEE guidelines. Larry will send him the forms.

5) Summary and discussion of next agenda

Attendance:

Name	Company	07 15 02	07 17 02	07 19 02	07 22 02	07 24 02	07 29 02	08 05 02	08 09 02	08 12 02	08 14 02
Albertsen, Dennis	Instrumentation Div. - Edwards AFB										
Bække, Jørgen	**Independent Consultant**	X		X		X	X	X		X	X
Buckner, Mark	Oak Ridge National Lab										
Catlin, Wayne	**Boeing**	X	X	X	X	X	X	X	X	X	X
Eccles, Lee	**Boeing**	X	X	X	X	X	X	X	X	X	X
GenKuong, Fernando	**Endevco**		X	X	X	X	X			X	X
Hambly, Richard M.	CNS Systems, Inc.		X								X
Jones, Charles	**Instrumentation Div. - Edwards AFB**	X	X		X	X	X				X
Lee, Kang	NIST		X			X					
Kemerling, Jim	TRIAD Semiconductor										
Lenarduzzi, Roberto	**ORNL**	X	X	X	X		X	X		X	
Licht, Torben	**B & K**	X	X	X	X	X	X	X	X	X	X
Lopez-Reyna, Carlos	Scitefair International, Inc.							X	X	X	X
Malchodi, Larry	**Boeing**				X	X	X	X	X	X	X
Maxwell, Daniel	**Walden Technology Source, Inc.**	X	X	X	X			X	X	X	X
Moore, Mike	ORNL						X				
Owen, Allan	**Eaton Corp.**	X		X	X	X	X			X	
Perrussel, David	Naval Surface Warfare Center		X	X			X				X
Randall, Bob	YSI										
Read, Jim	Moore Industries-International, Inc.	X	X	X	X						X
Segal, Andrew	Gigahertz Design Technology							X	X		
Sinclair, Bob	**NVE Corp.**	X	X	X	X	X	X	X	X		X
Slack, Mark	**Boeing**	X	X	X	X	X	X	X	X	X	X
Smith, Steve	ORNL	X				X			X	X	X
Tracy, Bryan	Harco Advanced Components			X							
		12	13	13	12	13	12	11	10	12	15